Conference Programme Day 1, Thursday February 14

Time	Topic	Speaker / Location
08:00-08:30	Conference Registration and Table Top & Poster Exhibition build up	Table Top & Poster Display Area
08:30-08:45	Welcome by the EIPC President	Alun Morgan, EIPC, UK
Keynote Session 1: New Business & Technology Roadmap for different market segments		**Moderator: Alun Morgan, EIPC, UK**
08:45-09:15	Business Outlook: Global Electronics Industry	Walt Custer, Custer Consulting, US
09:15-09:45	PCB Trends for Manufacturing- from Smartphone to Automotive	Erkko Helminen, TTM, FI
09:45-10:00	Panel discussion	
Session 2: New trends for Imaging of PCB's, Conductor & Solder Mask		**Moderator: Tarja Rapala-Virtanen, EIPC, FI**
10:00-10:20	Developing dry film for fine line following the evolution of exposure technologies	Ilaria Pasquali, Elga Europe, IT
10:20-10:40	Orbotech Diamond TM10 - Solder Mask at its best	Uwe Altmann, Orbotech, BE
10:40-11:00	The Importance of Reduction in Metal etching for Today's and Future PCB Designs	Hironori Takashima, MEC Europe, BE
11:00-11:30	**30 minutes Coffee break**	**Table Top & Poster Display Area**
11:30-11:50	Comparative Analysis of Multiple Laser Sources for Cutting/Ablation Efficacy and Quality on HDI PCB and ICP Materials	Nicolas Falletto, ESI, US
11:50-12:10	Recent developments with the Inkjet Soldermask	Don Monn, Taiyo America, US
12:10-12:30	PCB Automation - Green Manufacturing	Andreas Schatz, Atotech Electronics Equipment, DE
12:30-12:50	Panel discussion	
12:50-14:00	**Network Lunch**	**Hotel restaurant**
Session 3: New advanced Materials for future Electronics		**Moderator: Emma Hudson, Gen3 Systems, UK**
14:00-14:20	Thermal Management	Alun Morgan, Ventec Europe, UK
14:20-14:40	LCP for hermetically sealed sensing applications	Sven Johannsen, Dyconex, CH
14:40-15:00	Radar High Frequency	Roland Schönholz, Technolam, DE
15:00-15:20	Specifying PCB Materials for HSD and microwave/millimeter wave product performance	Chudy Roosevelt Nwachukwu, ITEQ, USA
15:20-15:40	Panel discussion	
16:00-19:00	**Departure & Visit Factory Elga Europe**	
19:30	**Network Dinner Milan Centre**	
22:30	**Departure to NH Hotel Milano Fiera**	

Conference Programme Day 2, Friday February 15

Session 4: New developments in PCB Technology, DFM and Cost Effective Supply Chain management		**Moderator: Dr. Michele Stampanoni, Cicor Group, CH**
09:00-09:20	PCB plating performance: know the layer thickness distribution before production starts	Robrecht Belis, Elsyca, Belgium
09:20-09:40	Tested PCB Quality. The impact on Supply Chain management, Final PCBA yield and Profitability	Roland Valentini, Gardien Group, DE
09:40-10:00	Thermal Management in PCBs, Benchmark of the Options and Future Possibilities for the Designers	Markku Jämsä, Aspocomp, FI
10:00-10:10	Panel discussion	
Session 5: New soldering Technology, Quality assurance and Durability testing		**Moderator: John Fix, Taiyo America, US**
10:10-10:30	The current state of the Solder Limits	Crystal Vanderpan, UL, US
10:30-10:50	CT scanning and tomographic imaging technology for failure analysis	Robert Boguski, Datest, US
10:50-11:10	Development of High Reliability No Clean Solder Paste	Dr. Lei Wang, Heraeus Deutschland, DE
11:10-11:40	**30 minutes Coffee break**	**Table Top & Poster Display Area**
11:40-12:00	Principles of Silver sintering and importance of PCB finish	Michiel de Monchy, MacDermid-Alpha, DE
12:00-12:20	New automated controlled impedance tester	Hermann Reischer, Polar Instruments, AT
12:20-12:40	Panel discussion	
12:40-12:50	**President closing remarks - End of Conference Day 2**	
12:50-14:00	**Network Lunch**	**Hotel restaurant**

The EIPC is not responsible for the content and the presentation of the technical papers, which rests with the presenters. Changes in the programme may occur, due to circumstances, for which the EIPC may not be held responsible.